

## Features

- Very Low On-resistance RDS(ON)
- Low Crss
- Fast switching
- Improved dv/dt capability

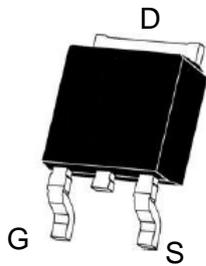
## Applications

- PWM Application
- Load Switch
- Power Management

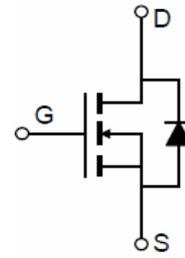


## Product Summary

$V_{DS}$	20	V
$R_{DS(on), Typ @ V_{GS}=4.5 V}$	20	mΩ
$I_D$	24	A



TO-252 top view



Schematic diagram

## Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Value	Units
$V_{DSS}$	Drain-Source Voltage	20	V
$I_D$	Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ )	20	A
		16	A
$I_{DM}$	Drain Current - Pulsed (Note 1)	60	A
$V_{GSS}$	Gate-Source Voltage	$\pm 10$	V
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	27	W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	4.6	$^\circ\text{C/W}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$

## Electrical Characteristics

 $T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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### Off Characteristics

$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	20	--	--	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 20\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	$\mu\text{A}$
		$V_{DS} = 1\text{ V}, T_C = 125^\circ\text{C}$	--	--	10	$\mu\text{A}$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 10\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -10\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	0.4	-	1.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 4.5\text{ V}, I_D = 8\text{ A}$	--	20	28	m $\Omega$
		$V_{GS} = 2.5\text{ V}, I_D = 6.6\text{ A}$	-	29	35	

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	259	-	pF
$C_{oss}$	Output Capacitance		--	51	-	pF
$C_{riss}$	Reverse Transfer Capacitance		--	47	-	pF

### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{GS} = 5\text{ V}, V_{DS} = 10\text{ V}, I_D = 20\text{ A},$ $R_G = 6\ \Omega, R_L = 2.7\ \Omega$	--	5.0	--	ns
$t_r$	Turn-On Rise Time		--	36	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	15	--	ns
$t_f$	Turn-Off Fall Time		--	5.4	--	ns
$Q_g$	Total Gate Charge	$V_{DS} = 10\text{ V}, I_D = 20\text{ A},$ $V_{GS} = 5\text{ V}$	--	4.2	--	nC
$Q_{gs}$	Gate-Source Charge		--	0.62	--	nC
$Q_{gd}$	Gate-Drain Charge		--	1.9	--	nC

### Drain-Source Diode Characteristics and Maximum Ratings

$I_S$	Maximum Continuous Drain-Source Diode Forward Current	--	--	24	A
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current	--	--	60	A
$V_{SD}$	Drain to Source Diode Forward Voltage, $V_{GS} = 0\text{ V}, I_{SD} = 4\text{ A}, T_J = 25^\circ\text{C}$	--	--	1.2	V

#### Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. Device mounted on FR-4 PCB, 1inch x 0.85inch x 0.062 inch
3. Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 0.5\%$

N- Channel Typical Characteristics

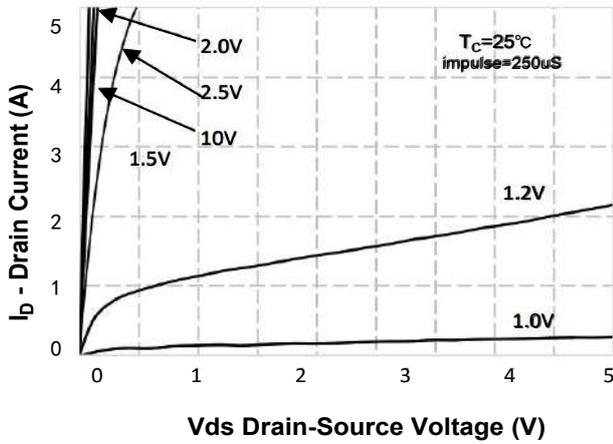


Figure 1. On-Region Characteristics

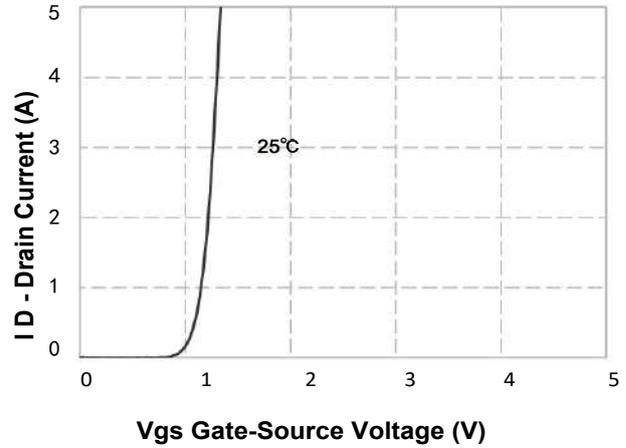


Figure 2. Transfer Characteristics

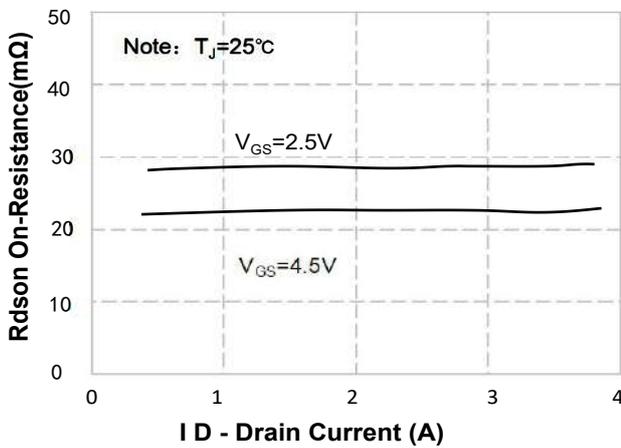


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

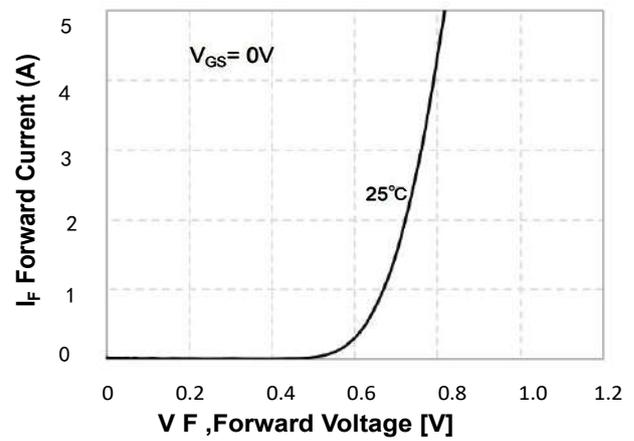


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

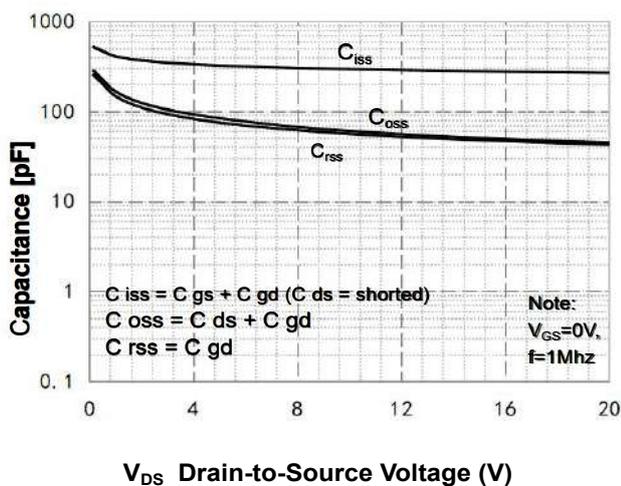


Figure 5. Capacitance Characteristics

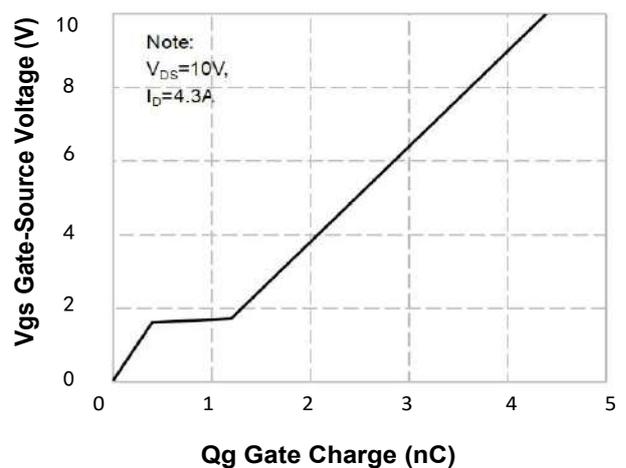


Figure 6. Gate Charge Characteristics

N- Channel Typical Characteristics (Continued)

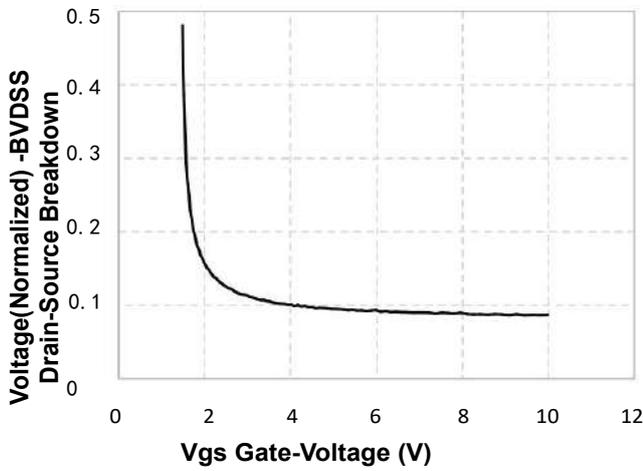


Figure 7. Breakdown Voltage Variation vs Gate-Voltage

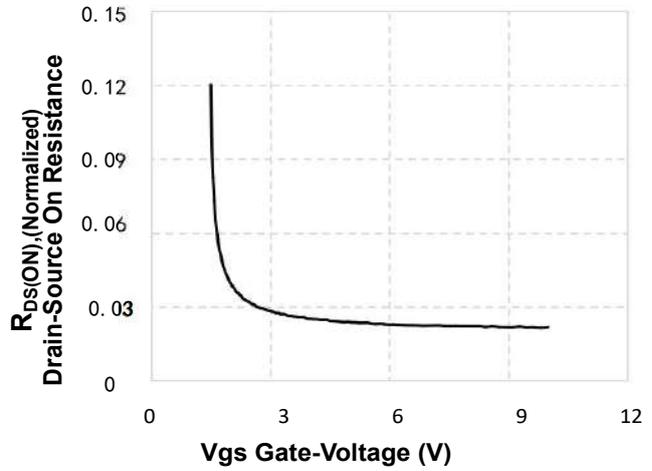


Figure 8. On-Resistance Variation vs Gate Voltage

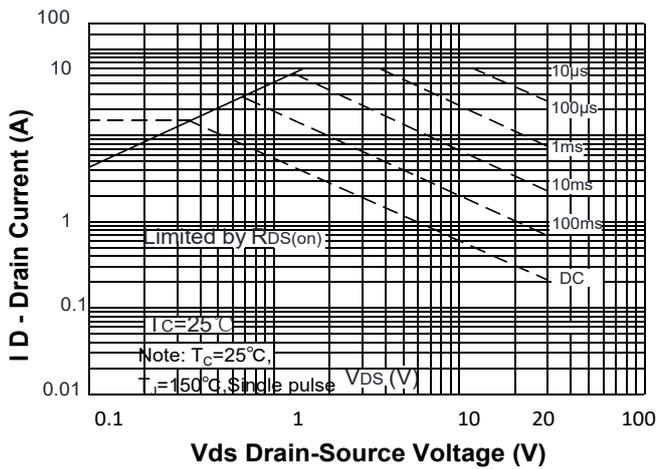


Figure 9. Maximum Safe Operating Area

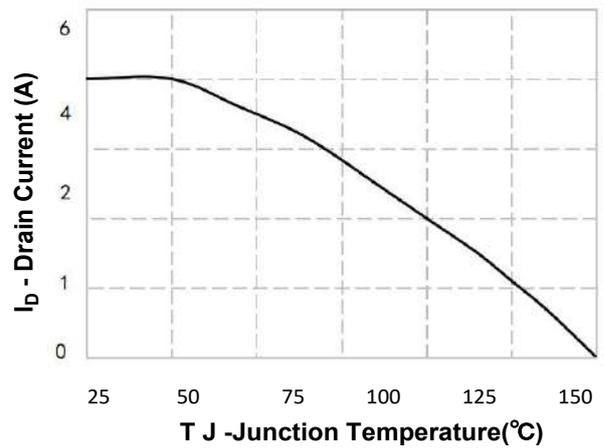


Figure 10. Maximum PContinuous Drain Current vs Case Temperature

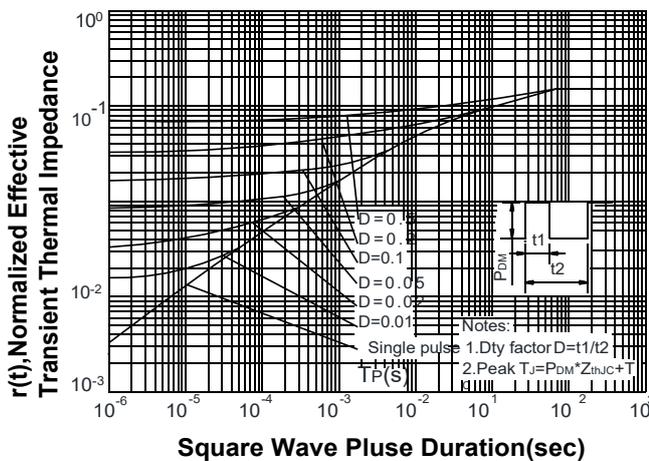
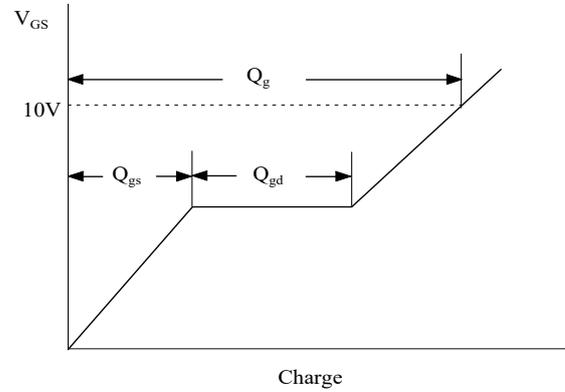
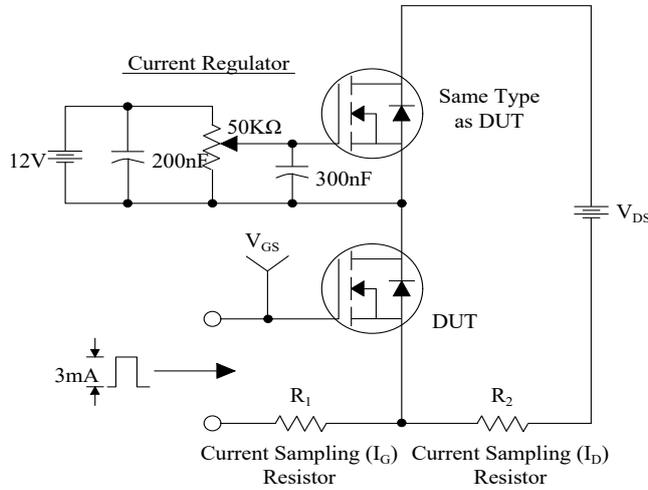
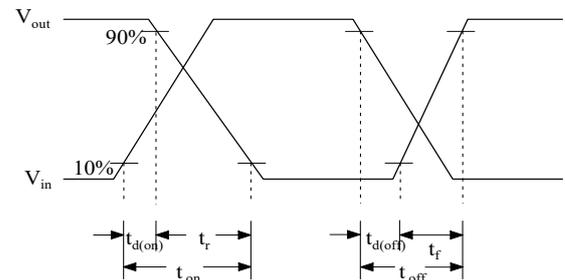
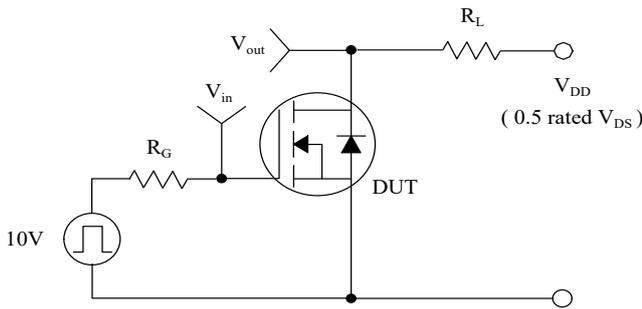


Figure 11. Transient Thermal Response Curve

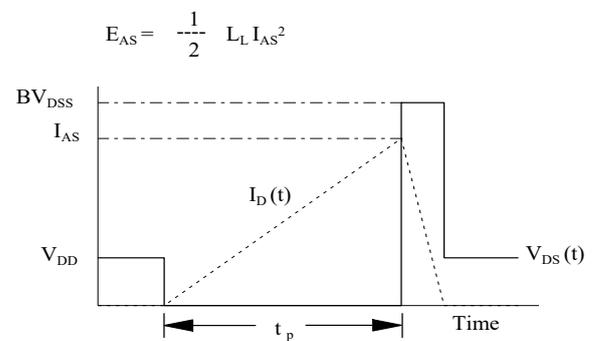
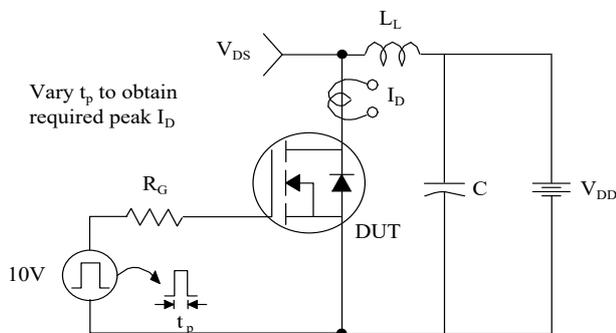
**Gate Charge Test Circuit & Waveform**



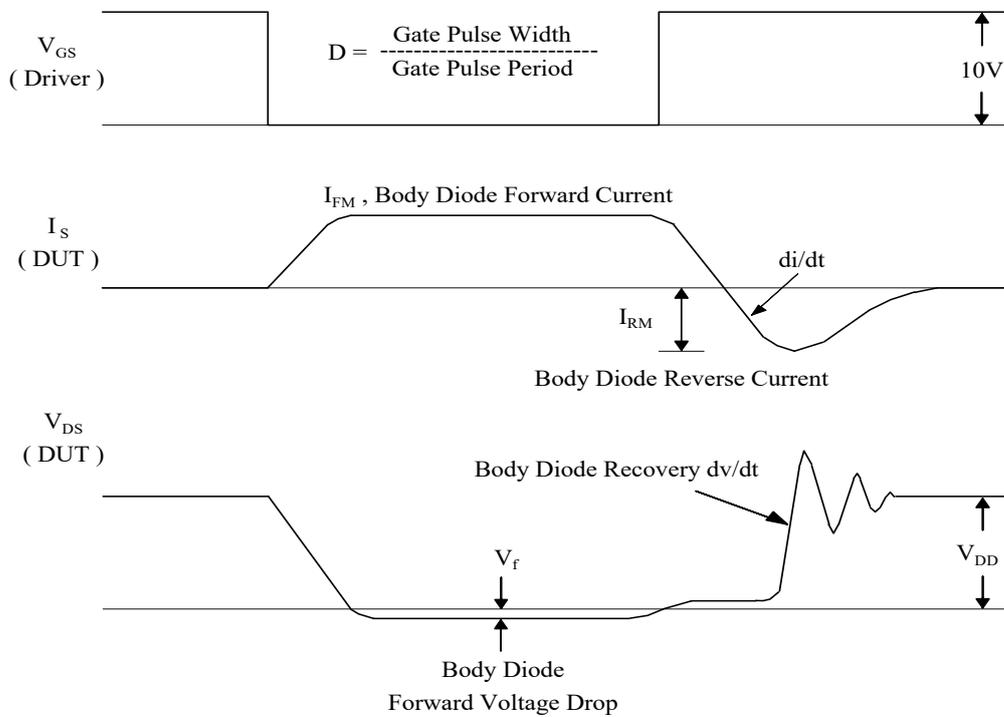
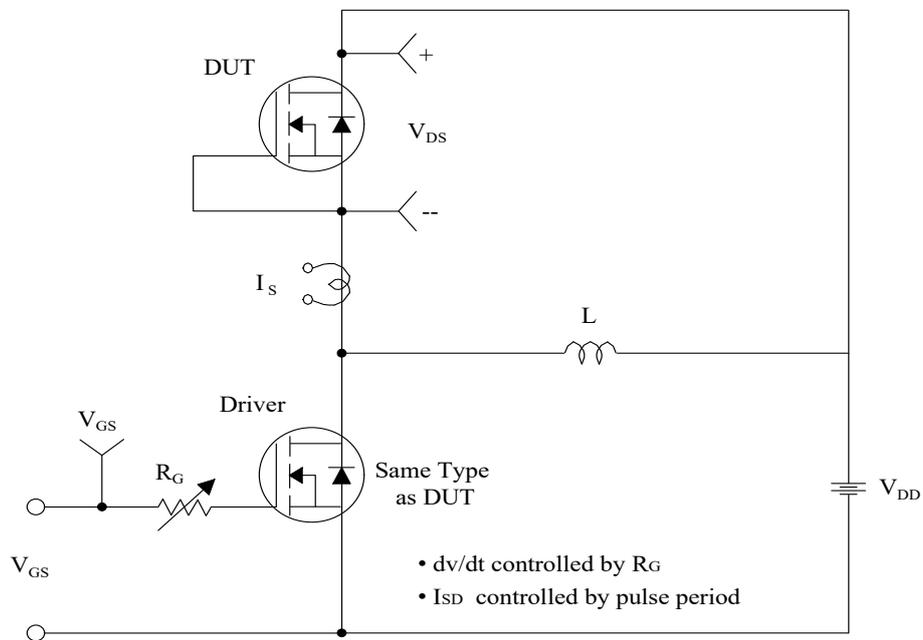
**Resistive Switching Test Circuit & Waveforms**



**Unclamped Inductive Switching Test Circuit & Waveforms**

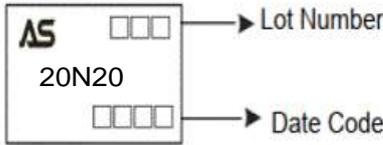


### Peak Diode Recovery dv/dt Test Circuit & Waveforms

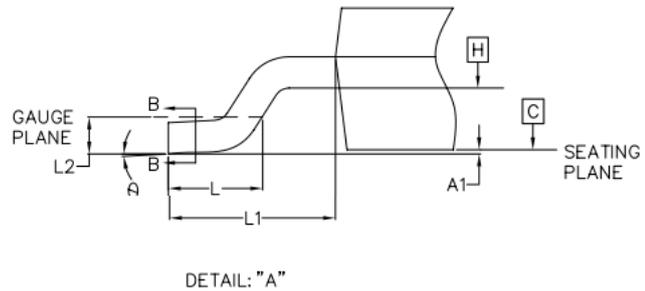
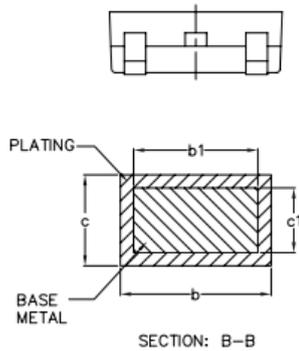
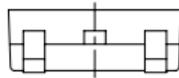
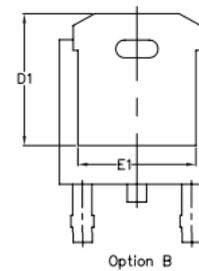
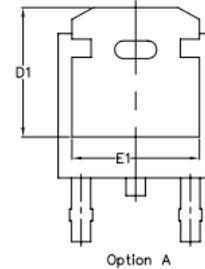
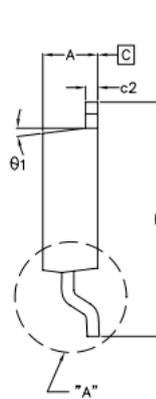
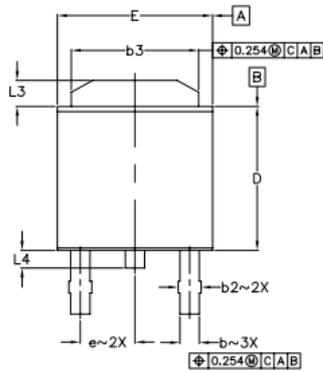


### Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
ASDM20N20KQ-R	20N20	TO-252	Tape&Reel	2500/Reel

PACKAGE	MARKING
TO-252	 <p>AS    □□□ → Lot Number 20N20 □□□□ → Date Code</p>

# TO-252



DIMENSIONS	COMMON			
	MM		INCH	
	MIN.	MAX.	MIN.	MAX.
A	2.184	2.387	0.086	0.094
A1	—	0.127	—	0.005
b	0.750	0.890	0.029	0.035
b1	0.750	0.860	0.029	0.034
b2	0.762	1.143	0.030	0.045
b3	4.953	5.461	0.195	0.215
c	0.460	0.610	0.018	0.024
c1	0.410	0.559	0.016	0.022
c2	0.460	0.889	0.018	0.035
D	5.969	6.223	0.235	0.245
D1	5.207	—	0.205	—
E	6.350	6.731	0.250	0.265
E1	4.318	—	0.170	—
e	2.290 BSC		0.090 BSC	
H	9.398	10.414	0.370	0.410
L	1.397	1.778	0.055	0.070
L1	2.743 BSC		0.108 BSC	
L2	0.508 BSC		0.020 BSC	
L3	0.889	1.270	0.035	0.050
L4	—	1.016	—	0.040
θ	0°	10°	0°	10°
θ1	0°	15°	0°	15°

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